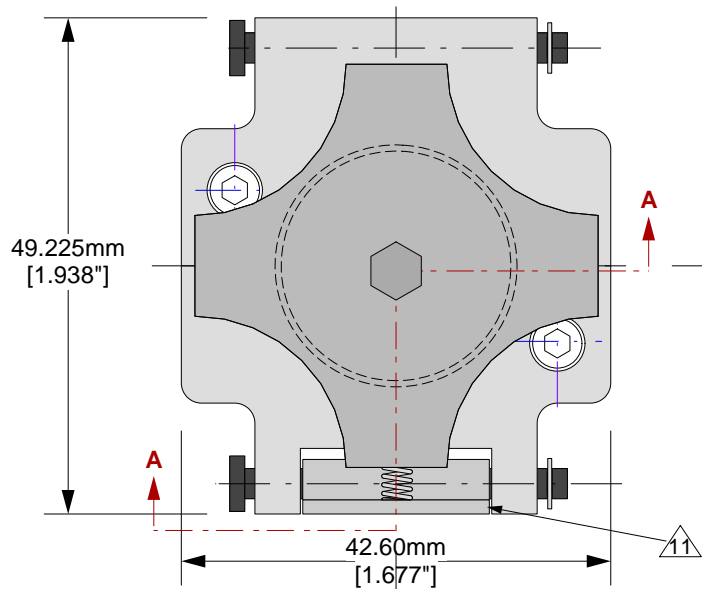
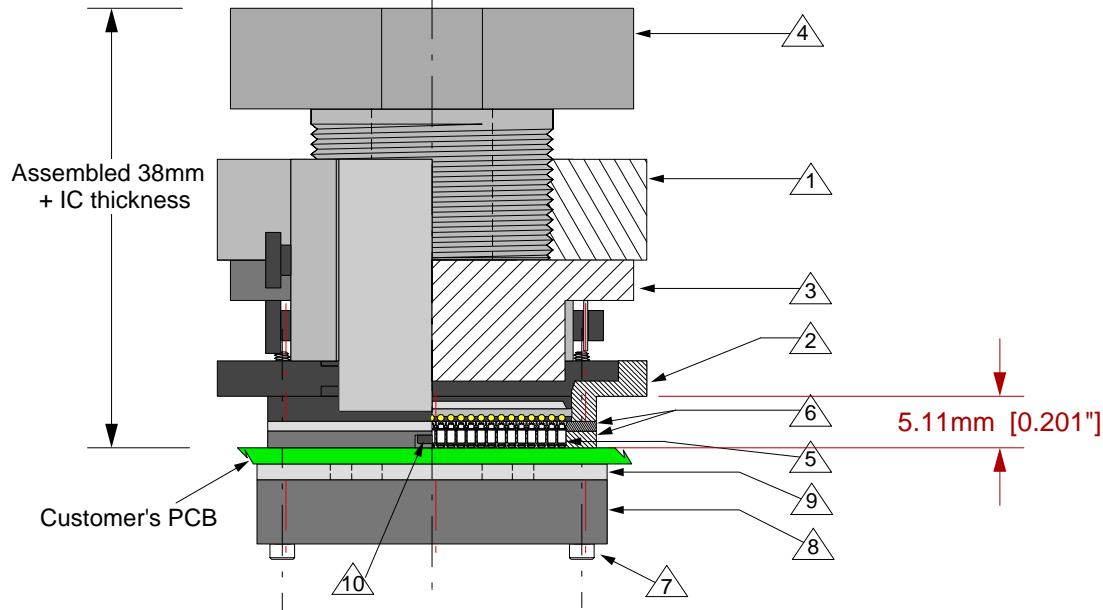


Top View



Side View
(Section AA)




Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes forces evenly
- Clamshell lid

Materials:

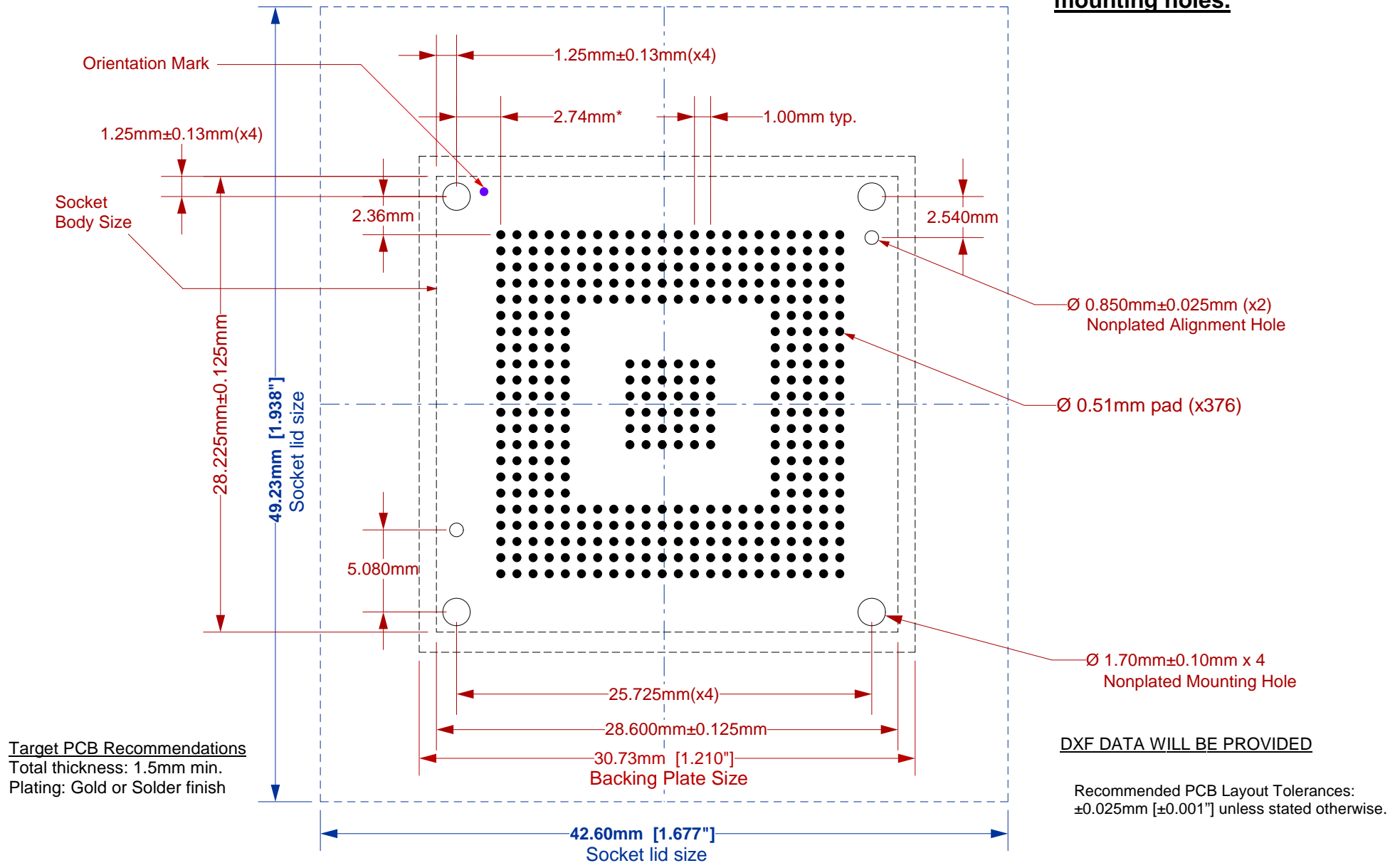
- 1 Clam Shell Lid: Black anodized Aluminum. Height = 20 mm.
- 2 Socket Base: Black anodized Aluminum. Height = 6 mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 12 mm.
- 4 Compression Screw: Clear anodized Aluminum. Height = 27 mm, Fluted Knob
- 5 Pogo Pin:
Plungers - Hardened Steel/ Gold plated
Barrel - Copper Alloy/ Gold plated
Spring - Stainless Steel/ Gold wire
- 6 Pogo Pin Guides: Torton or Peek.
- 7 Socket Base Screw: Socket Head Cap Screw, 18-8 SS, 0-80 Thread, 3/4" long.
- 8 Backing Plate: Black anodized Aluminum
- 9 Insulation Plate: FR4/G10
- 10 Pogo Pin Guide Screw: Pan head phillips, 18-8 SS, 0-80 thread, 3/16" long.
- 11 Latch: Black anodized Aluminum.


	SS-BGA376A-01 Drawing	Status: Released	Scale: 1.25:1	Rev: A
	© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr. Ste 400 Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: J. Glab	Date: 05/25/07	
		File: SS-BGA376A-01 Dwg	Modified:	

All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

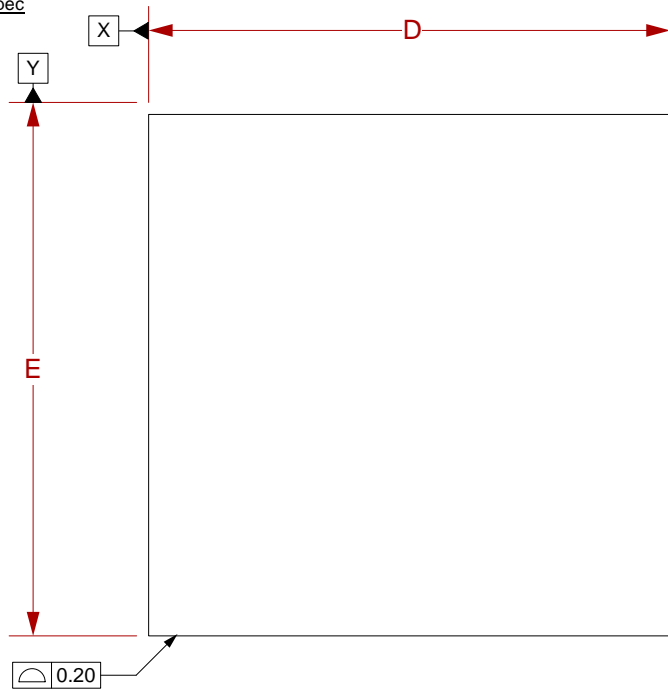
Recommended PCB Layout
Top View

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**

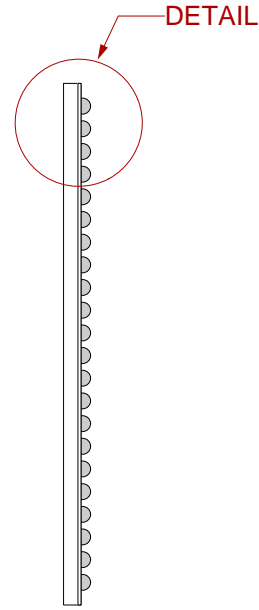


 <p>© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr. Ste 400 Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	<p>SS-BGA376A-01 Drawing</p>	<p>Status: Released</p>	<p>Scale: 1.25:1</p>	<p>Rev: A</p>
	<p>Drawing: J. Glab</p>	<p>Date: 05/25/07</p>		
	<p>File: SS-BGA376A-01 Dwg</p>	<p>Modified:</p>		

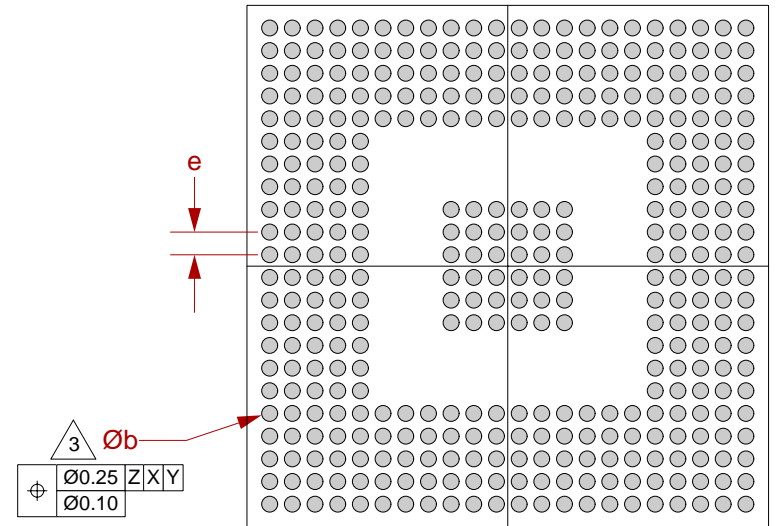
Compatible BGA Spec



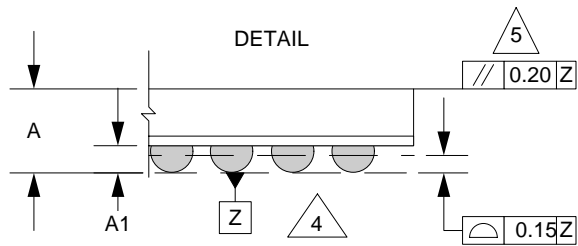
TOP VIEW



SIDE VIEW




BOTTOM VIEW



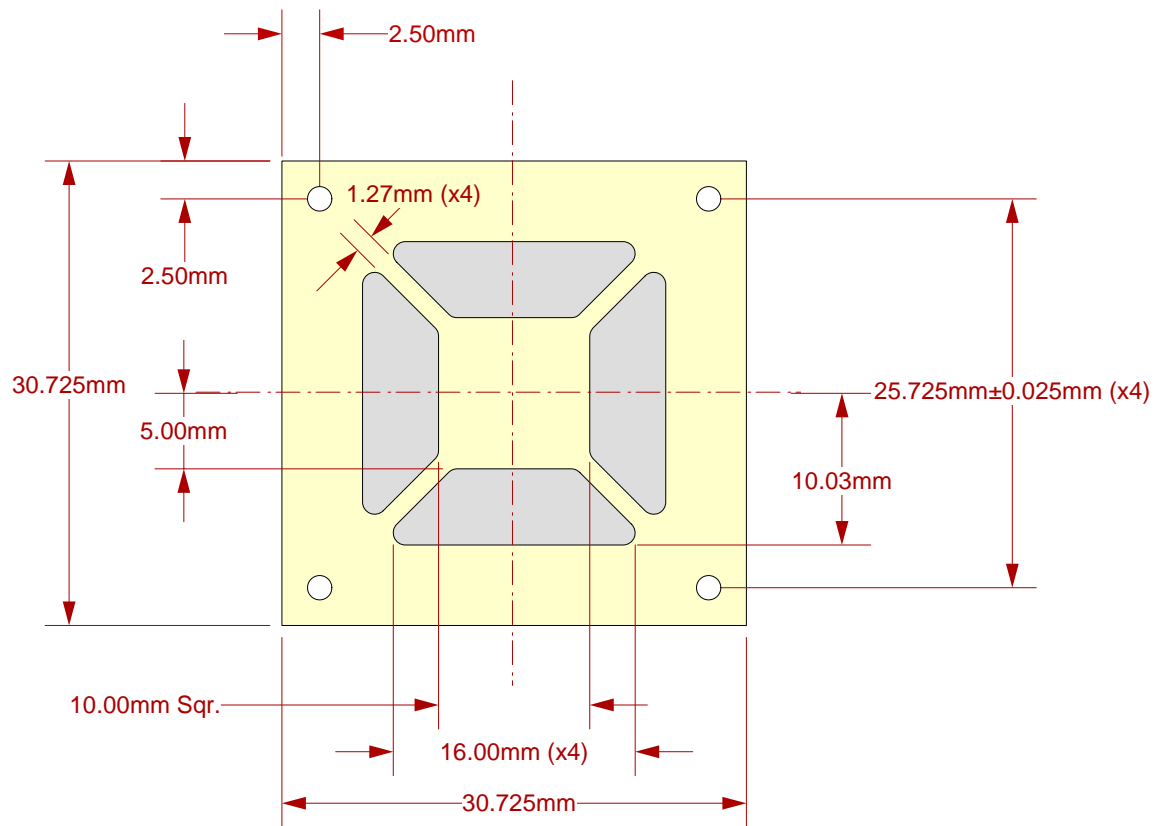
1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
 - 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 - 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.16
A1	0.4	0.6
b		0.7
D	23.00 BSC	
E	23.00 BSC	
e	1.0 BSC	

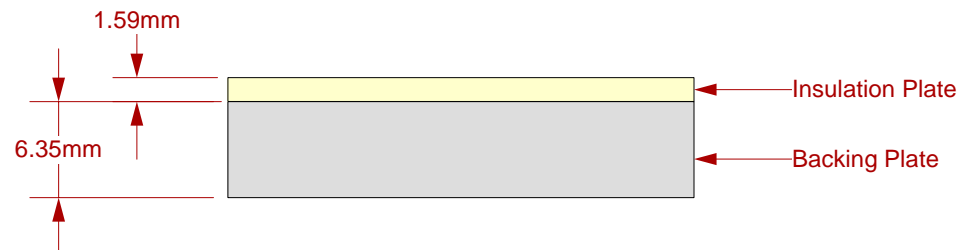
22x22 Array

	SS-BGA376A-01 Drawing	Status: Released	Scale: 1.25:1	Rev: A
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		File: SS-BGA376A-01 Dwg		Modified:


Top View



Side View

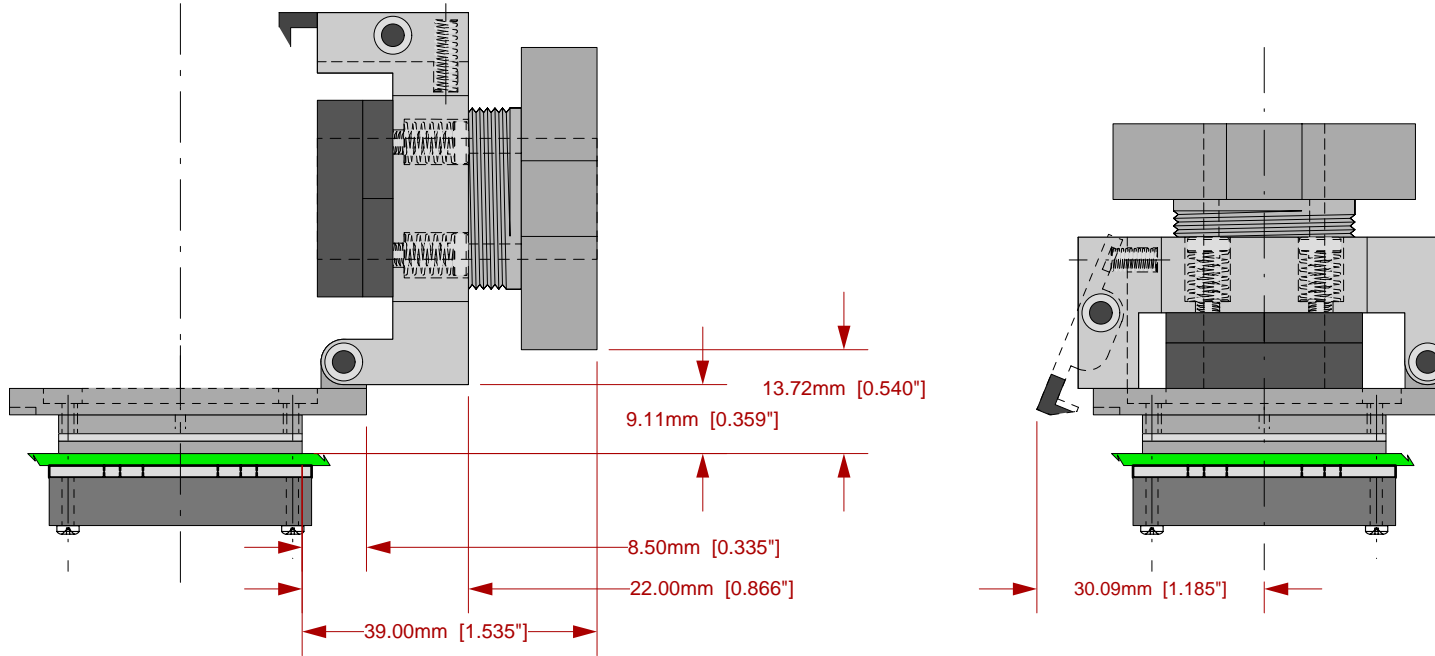
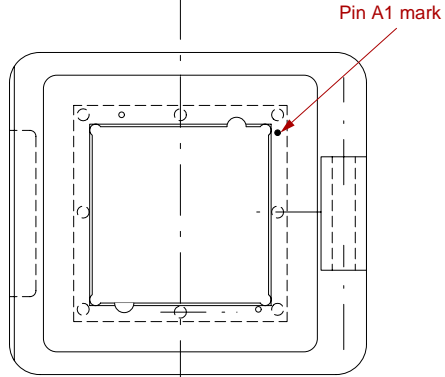



Description: Backing Plate with Insulation Plate

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		File: SS-BGA376A-01 Dwg	Modified:	

All dimensions are in mm.
All tolerances are +/- 0.125mm.
(Unless stated otherwise)

Top View of Socket Base



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		File: SS-BGA376A-01 Dwg	Modified:	

All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.